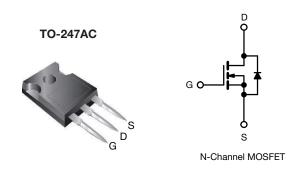
Vishay Siliconix

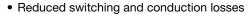
## **EL Series Power MOSFET**



PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.155			
Q <sub>g</sub> max. (nC)	8	2			
Q <sub>gs</sub> (nC)	2	0			
Q <sub>gd</sub> (nC)	1	3			
Configuration	Sin	Single			

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)



- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION			
Package	TO-247AC		
Lead (Pb)-free and halogen-free	SiHG22N60AEL-GE3		

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	600	V	
Gate-source voltage			$V_{GS}$	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Continuous drain current (T <sub>J</sub> = 150 °C)	\/ at 10 \/	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	- I <sub>D</sub>	21		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		13	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	48		
Linear derating factor				1.7	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	183	mJ	
Maximum power dissipation			$P_{D}$	208	W	
Operating junction and storage temperature range				-55 to +150	°C	
Reverse diode dv/dt <sup>d</sup>		dv/dt	50	V/ns		
Soldering recommendations (peak temperature) <sup>c</sup>	For 10 s		·	260	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 3.6 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	=	40	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.6	C/VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static		-				•			
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	600	-	-	V			
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.68	-	V/°C		
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	- V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V		
				V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ		
		V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	-	1	μΑ		
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	10			
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.155	0.180	Ω		
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 8 V, I <sub>D</sub> = 11 A		-	16	-	S		
Dynamic									
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	1757	-	pF		
Output capacitance	C <sub>oss</sub>			-	74	-			
Reverse transfer capacitance	C <sub>rss</sub>			-	6	-			
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	48	-			
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	257	-			
Total gate charge	Qg			-	41	82	1		
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		10	-	nC		
Gate-drain charge	Q <sub>gd</sub>				13	-			
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 11 A,		-	27	54			
Rise time	t <sub>r</sub>			-	24	48			
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		86	172	ns		
Fall time	t <sub>f</sub>	1		-	28	56			
Gate input resistance	$R_g$	f = 1 MHz, open drain		3.6	7.2	14.4	Ω		
Drain-Source Body Diode Characteristic	s	-				•			
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21			
Pulsed diode forward current	I <sub>SM</sub>			-	-	48	- A		
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		-	-	1.2	V		
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	285	570	ns		
Reverse recovery charge	Q <sub>rr</sub>			-	4.1	8.2	μC		
Reverse recovery current	I <sub>RRM</sub>			_	27	_	Α		

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$  b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

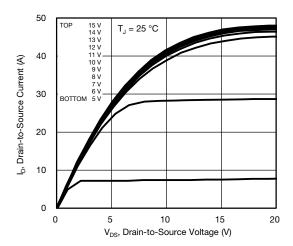


Fig. 1 - Typical Output Characteristics

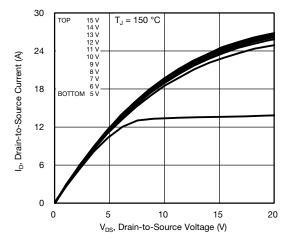


Fig. 2 - Typical Output Characteristics

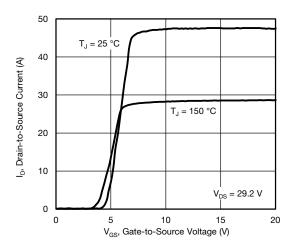


Fig. 3 - Typical Transfer Characteristics

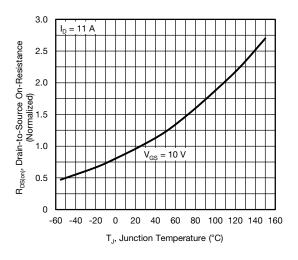


Fig. 4 - Normalized On-Resistance vs. Temperature

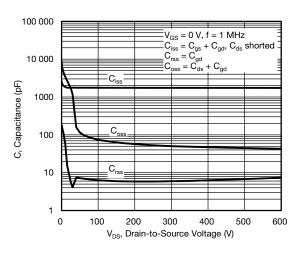


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

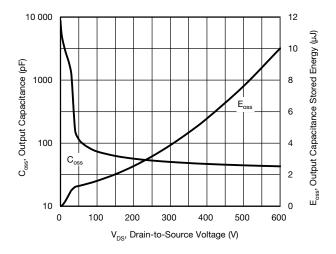


Fig. 6 -  $C_{\text{oss}}$  and  $E_{\text{oss}}$  vs.  $V_{\text{DS}}$ 



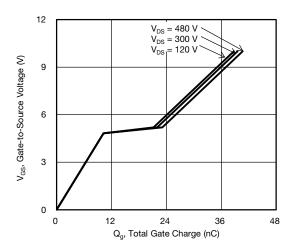


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

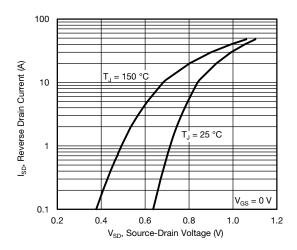


Fig. 8 - Typical Source-Drain Diode Forward Voltage

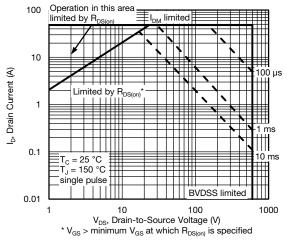


Fig. 9 - Maximum Safe Operating Area

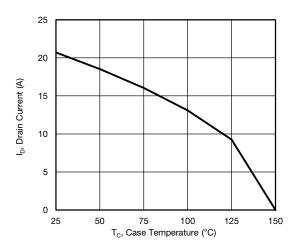


Fig. 10 - Maximum Drain Current vs. Case Temperature

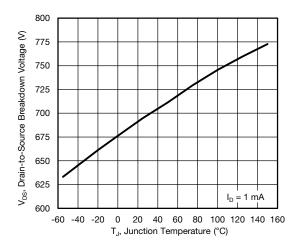


Fig. 11 - Temperature vs. Drain-to-Source Voltage



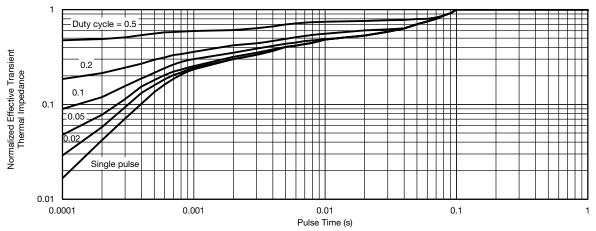


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

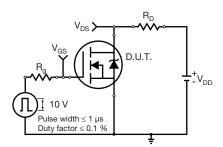


Fig. 13 - Switching Time Test Circuit

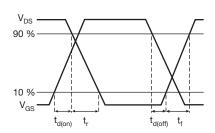


Fig. 14 - Switching Time Waveforms

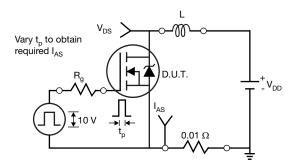


Fig. 15 - Unclamped Inductive Test Circuit

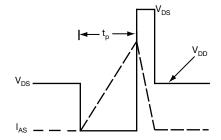


Fig. 16 - Unclamped Inductive Waveforms

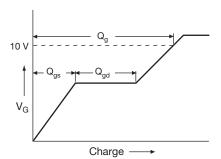


Fig. 17 - Basic Gate Charge Waveform

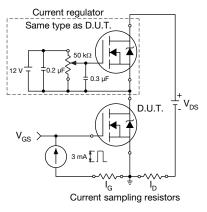
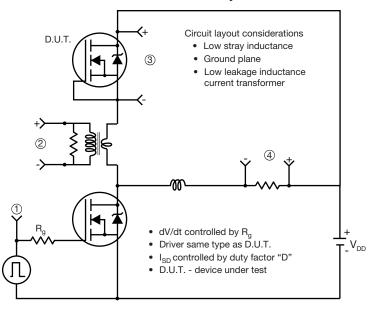


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



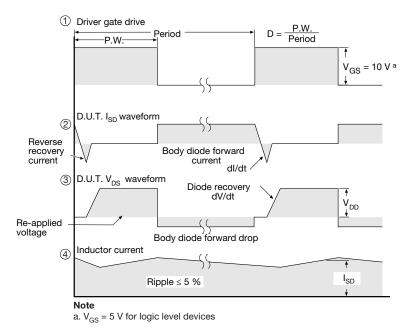


Fig. 19 - For N-Channel

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